

FFM101-MH1 THRU FFM107-MH1

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FFM101-MH1 THRU FFM107-MH1

1.0A Surface Mount Fast Recovery Rectifiers-50-1000V

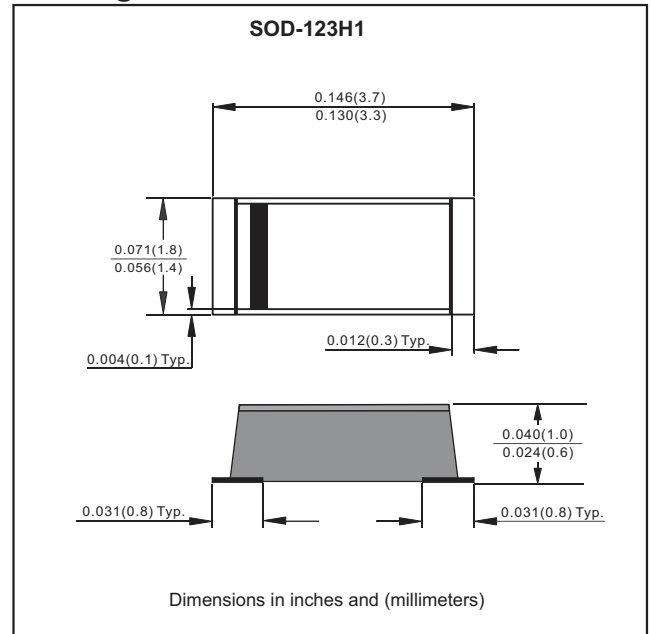
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- Tiny plastic SMD package.
- High current capability.
- Fast switching for high efficiency.
- High surge current capability.
- Glass passivated chip junction.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex. FFM101-MH1-H.

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123H1
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.0103 gram

Package outline



Maximum ratings and Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

| PARAMETER | SYMBOLS | FFM101-MH1 | FFM102-MH1 | FFM103-MH1 | FFM104-MH1 | FFM105-MH1 | FFM106-MH1 | FFM107-MH1 | UNIT |
|--|-----------------|-------------|------------|------------|------------|------------|------------|------------|--------------------------------|
| Maximum repetitive peak reverse voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC blocking voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum average forward rectified current | I_O | 1.0 | | | | | | | A |
| Peak forward surge current 8.3ms single half sine-wave(JEDEC method) | I_{FSM} | 25 | | | | | | | A |
| Maximum forward voltage at $I_F=1.0A$ | V_F | 1.30 | | | | | | | V |
| Maximum DC reverse current $T_J=25^{\circ}\text{C}$ at rated DC blocking voltage $T_J=125^{\circ}\text{C}$ | I_R | 5.0 100 | | | | | | | μA μA |
| Typical thermal resistance junction to ambient | $R_{\theta JA}$ | 73 | | | | | | | $^{\circ}\text{C}/\text{W}$ |
| Typical thermal resistance junction to case | $R_{\theta JC}$ | 53 | | | | | | | $^{\circ}\text{C}/\text{W}$ |
| Typical junction capacitance (Note 2) | C_J | 15 | | | | | | | pF |
| Maximum reverse recovery time (Note 1) | t_{rr} | 150 | | | 250 | | 500 | | ns |
| Operating junction temperature range | T_J | -55 to +150 | | | | | | | $^{\circ}\text{C}$ |
| Storage temperature range | T_{STG} | -65 to +175 | | | | | | | $^{\circ}\text{C}$ |

Note 1. Reverse recovery time test condition, $I_F=0.5A$, $I_R=1.0A$, $I_{RR}=0.25A$
 2. Measured at 1 MHz and applied reverse voltage of 4.0 VDC

Rating and characteristic curves (FFM101-MH1 THRU FFM107-MH1)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

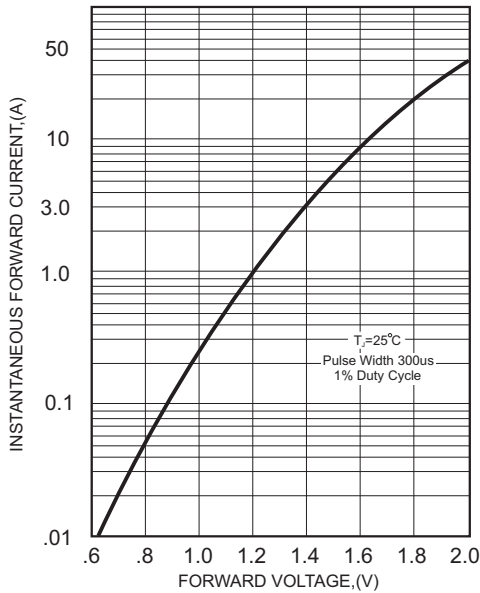


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

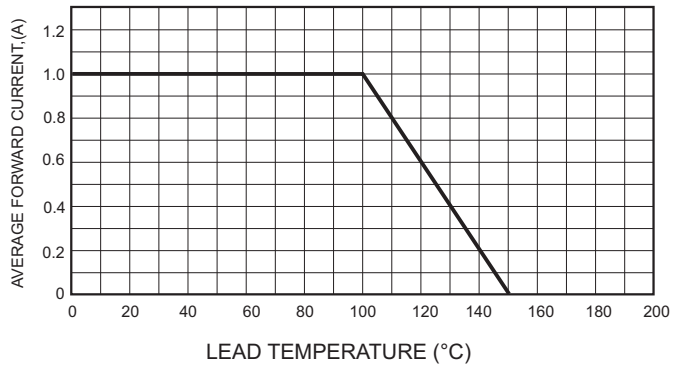


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

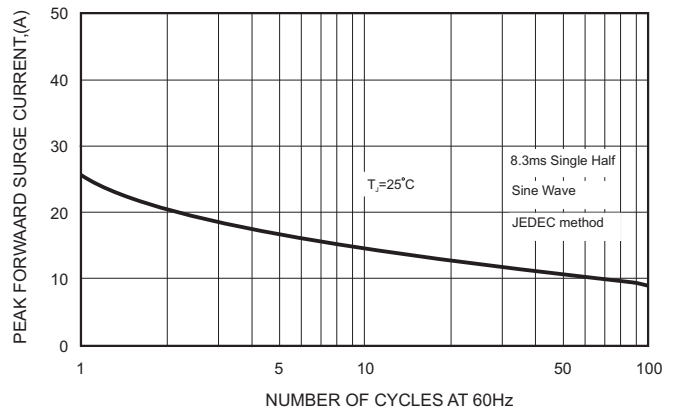
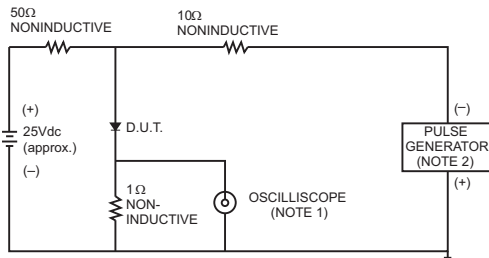


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



- NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.
 2. Rise Time= 10ns max., Source Impedance= 50 ohms.

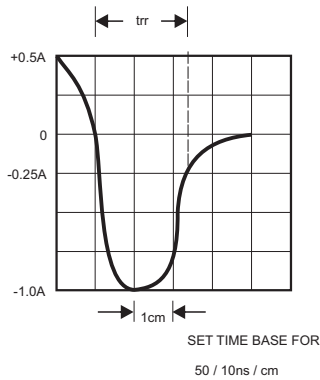
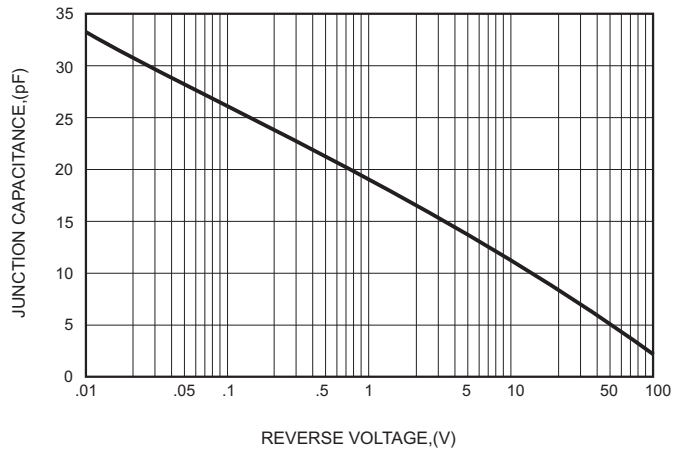




FIG.5-TYPICAL JUNCTION CAPACITANCE



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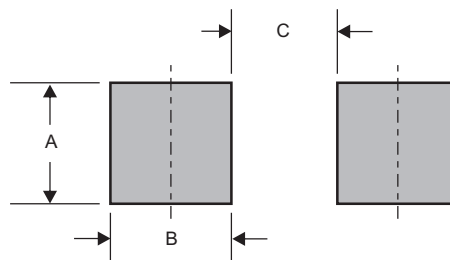
Pinning information

| Pin | Simplified outline | Symbol |
|----------------------------|---|---|
| Pin1 cathode Pin2 anode |  |  |

Marking

| Type number | Marking code |
|-------------|--------------|
| FFM101-MH1 | F1 |
| FFM102-MH1 | F2 |
| FFM103-MH1 | F3 |
| FFM104-MH1 | F4 |
| FFM105-MH1 | F5 |
| FFM106-MH1 | F6 |
| FFM107-MH1 | F7 |

Suggested solder pad layout

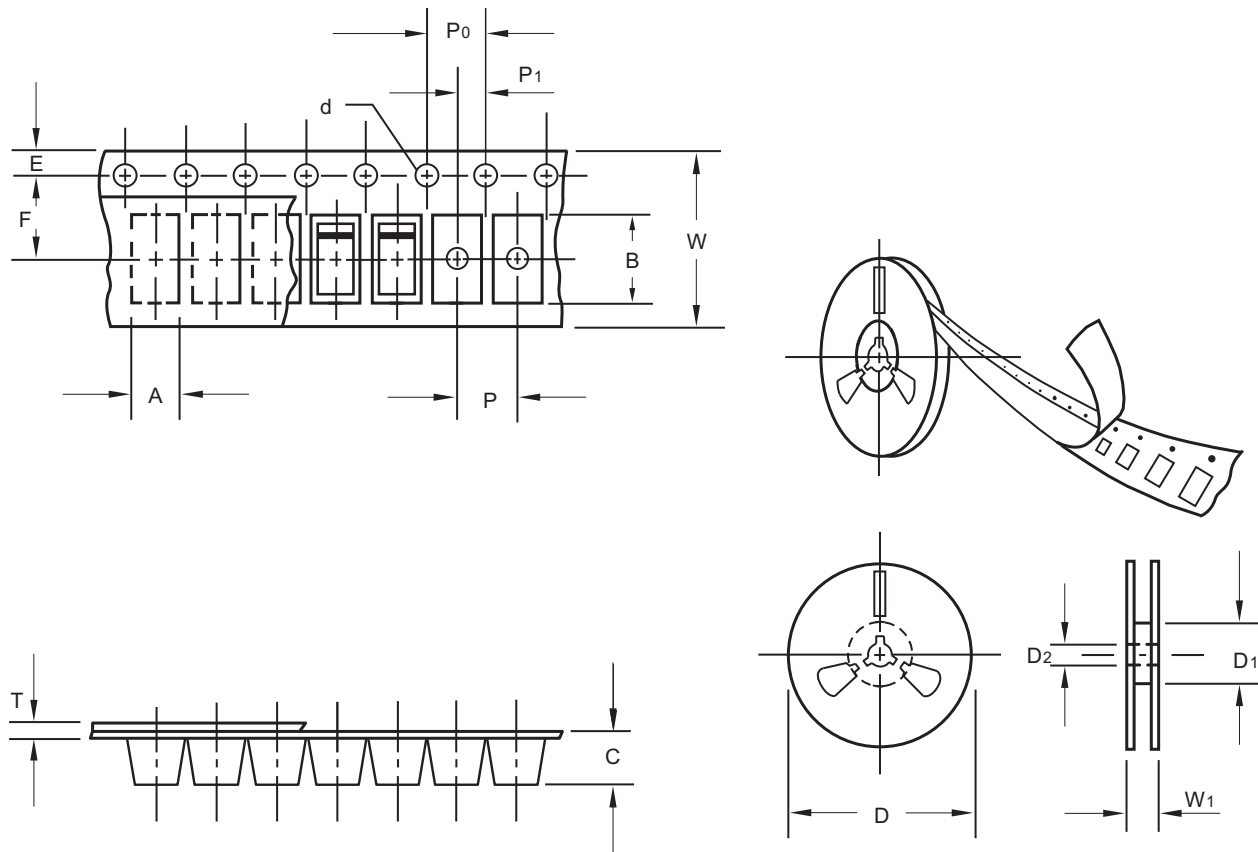


Dimensions in inches and (millimeters)

| PACKAGE | A | B | C |
|-----------|--------------|--------------|--------------|
| SOD-123H1 | 0.071 (1.80) | 0.051 (1.30) | 0.067 (1.70) |

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Packing information



unit:mm

| Item | Symbol | Tolerance | SOD-123H1 |
|---------------------------|--------|-----------|-----------|
| Carrier width | A | 0.1 | 2.00 |
| Carrier length | B | 0.1 | 3.85 |
| Carrier depth | C | 0.1 | 1.10 |
| Sprocket hole | d | 0.1 | 1.50 |
| 13" Reel outside diameter | D | 2.0 | - |
| 13" Reel inner diameter | D1 | min | - |
| 7" Reel outside diameter | D | 2.0 | 178.00 |
| 7" Reel inner diameter | D1 | min | 62.00 |
| Feed hole diameter | D2 | 0.5 | 13.00 |
| Sprocket hole position | E | 0.1 | 1.75 |
| Punch hole position | F | 0.1 | 3.50 |
| Punch hole pitch | P | 0.1 | 4.00 |
| Sprocket hole pitch | P0 | 0.1 | 4.00 |
| Embossment center | P1 | 0.1 | 2.00 |
| Overall tape thickness | T | 0.1 | 0.23 |
| Tape width | W | 0.3 | 8.00 |
| Reel width | W1 | 1.0 | 11.40 |

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

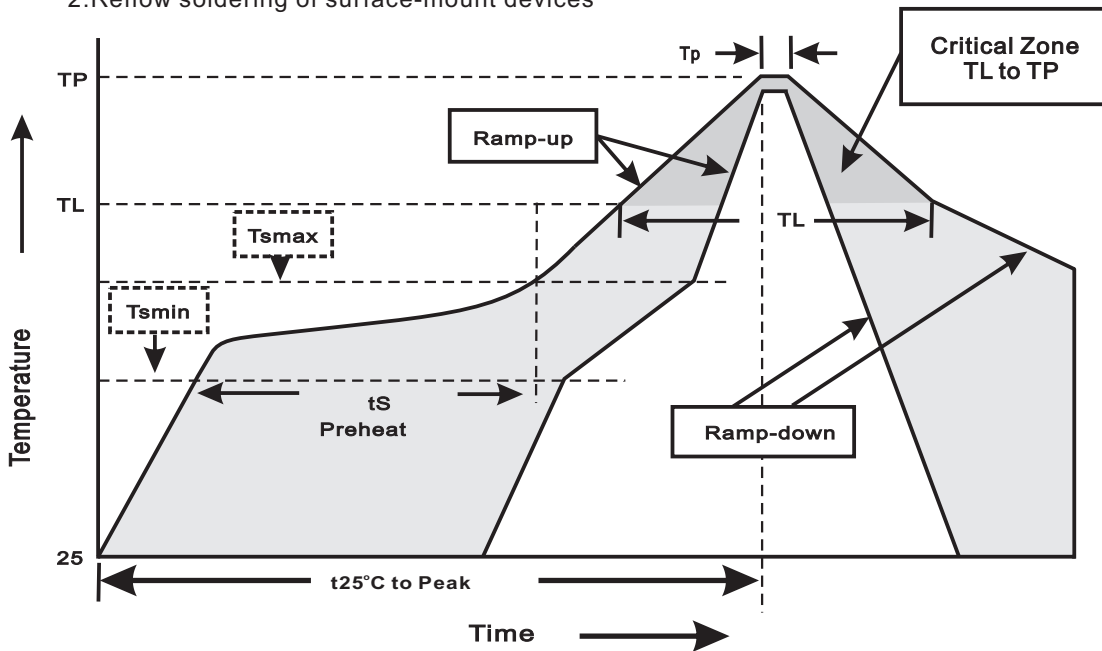
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Reel packing

| PACKAGE | REEL SIZE | REEL (pcs) | COMPONENT SPACING (m/m) | BOX (pcs) | INNER BOX (m/m) | REEL DIA, (m/m) | CARTON SIZE (m/m) | CARTON (pcs) | APPROX. GROSS WEIGHT (kg) |
|-----------|-----------|------------|-------------------------|-----------|-----------------|-----------------|-------------------|--------------|---------------------------|
| SOD-123H1 | 7" | 3,000 | 4.0 | 30,000 | 183*123*183 | 178 | 382*257*387 | 240,000 | 9.0 |

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

| Profile Feature | Soldering Condition |
|--|-----------------------------|
| Average ramp-up rate(TL to TP) | <3°C/sec |
| Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts) | 150°C 200°C 60~120sec |
| Tsmax to TL -Ramp-upRate | <3°C/sec |
| Time maintained above: -Temperature(TL) -Time(tL) | 217°C 60~260sec |
| Peak Temperature(TP) | 255°C-0/+5°C |
| Time within 5°C of actual Peak Temperature(tp) | 10~30sec |
| Ramp-down Rate | <6°C/sec |
| Time 25°C to Peak Temperature | <6minutes |

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High reliability test capabilities

| Item Test | Conditions | Reference |
|-----------------------------------|--|-------------------------------|
| 1. Solder Resistance | at 260±5°C for 10±2sec. | MIL-STD-750D METHOD-2031 |
| 2. Solderability | at 245±5°C for 5 sec. | MIL-STD-202F METHOD-208 |
| 3. High Temperature Reverse Bias | $V_R=80\%$ rate at $T_J=150^\circ\text{C}$ for 168 hrs. | MIL-STD-750D METHOD-1038 |
| 4. Forward Operation Life | Rated average rectifier current at $T_A=25^\circ\text{C}$ for 500hrs. | MIL-STD-750D METHOD-1027 |
| 5. Intermittent Operation Life | $T_A = 25^\circ\text{C}$, $I_F = I_o$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles. | MIL-STD-750D METHOD-1036 |
| 6. Pressure Cooker | 15P _{SIG} at $T_A=121^\circ\text{C}$ for 4 hrs. | JESD22-A102 |
| 7. Temperature Cycling | -55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles. | MIL-STD-750D METHOD-1051 |
| 8. Forward Surge | 8.3ms single half sine-wave , one surge. | MIL-STD-750D METHOD-4066-2 |
| 9. Humidity | at $T_A=85^\circ\text{C}$, RH=85% for 1000hrs. | MIL-STD-750D METHOD-1021 |
| 10. High Temperature Storage Life | at 175°C for 1000 hrs. | MIL-STD-750D METHOD-1031 |